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Bib Data Sheet

CONFIRMATION NO. 3160

SERIAL NUMBER 10/801,386	FILING DATE 03/15/2004  RULE	CLASS 257	GROUP ART UNIT 2814	ATTORNEY DOCKET NO. 500180.03 (29249/US/2)
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## APPLICANTS

Tongbi Jiang, Boise, ID; *WSL*

## \*\* CONTINUING DATA \*\*\*\*\*

This application is a CON of 09/895,662 06/29/2001 PAT 6,710,462 *WSL*  
 which is a DIV of 09/515,579 02/29/2000 PAT 6,524,891

## \*\* FOREIGN APPLICATIONS \*\*\*\*\*

## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 06/01/2004

Foreign Priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	STATE OR COUNTRY ID	SHEETS DRAWING 2	TOTAL CLAIMS 16	INDEPENDENT CLAIMS 2
35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance	Verified and Acknowledged Examiner's Signature <i>WSL</i> Initials <i>WSL</i>			

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## TITLE

Pressure and heat cured semiconductor die packages having reduced voids in a die attach bondline

FILING FEE  RECEIVED 770	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:	<input type="checkbox"/> All Fees <input type="checkbox"/> 1.16 Fees ( Filing ) <input type="checkbox"/> 1.17 Fees ( Processing Ext. of time ) <input type="checkbox"/> 1.18 Fees ( Issue ) <input type="checkbox"/> Other _____ <input type="checkbox"/> Credit
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